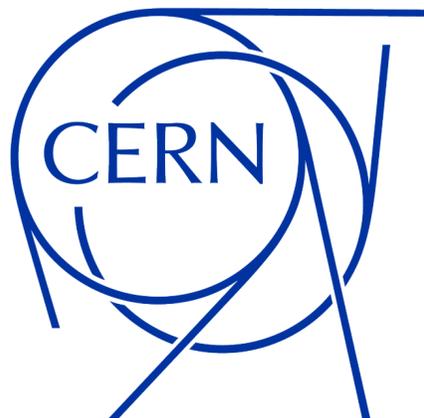


ALICE

Development path for a Vertex Detector Pixel Sensor





Introduction — main objectives

- **Pointing resolution**

- position resolution ($2.5 \mu\text{m}$) → pixel pitch ($O(10 \mu\text{m})$) \perp low power consumption
- material budget $0.1\% X_0/\text{layer}$ → low power consumption
- ⇒ Power consumption per pixel is crucial

- **Pb-Pb operation**

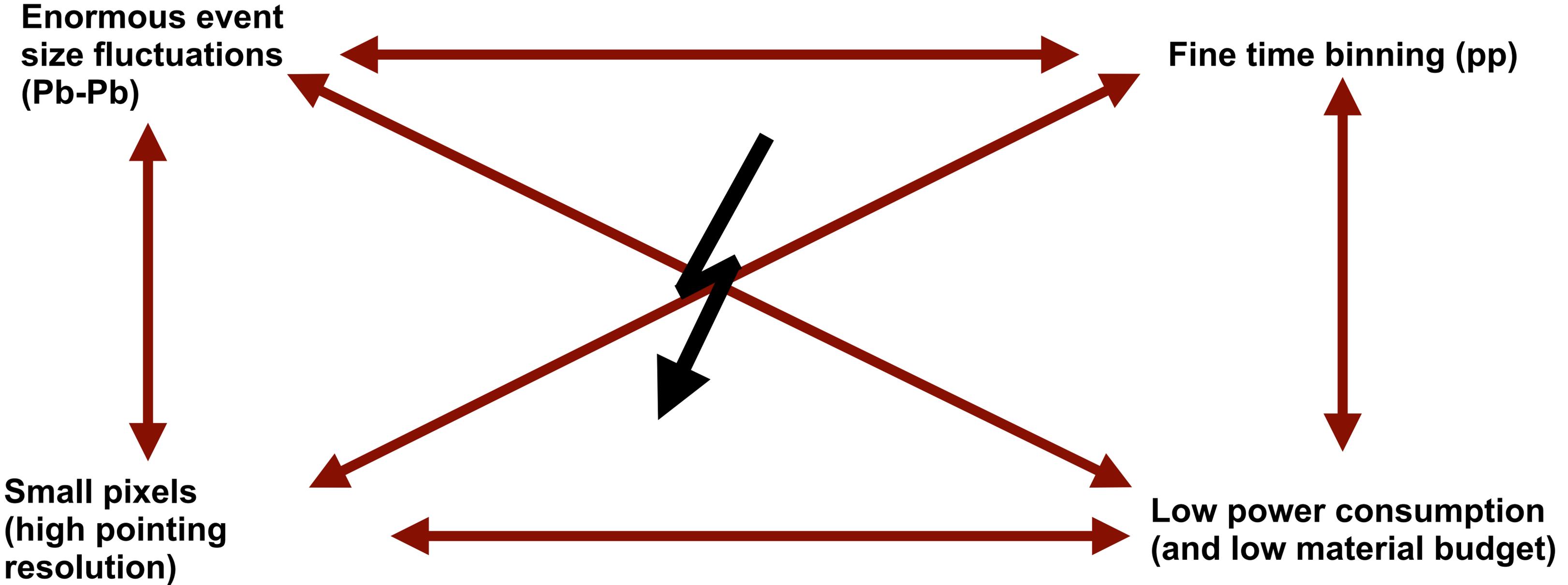
- enormous event size fluctuations
- large bandwidth or buffering close to the pixel needed
- more complex digital circuitry
 - \perp small footprint and/or low power consumption

- **pp operation**

- high event rate (24 MHz) → time resolution ($O(100 \text{ ns})$) needed to limit pile up
 - \perp low power consumption
- large statistics required → high radiation tolerance required → favouring smaller pixel pitch



Introduction — main objectives (continued)





ALICE 3 vertex and tracking detector requirements

Updated for ~300 kHz Pb-Pb

	ALICE ITS3	ALICE 3	
		Vertex Detector	Tracker (ML/OT)
Position resolution (μm)	5	2.5	10
Pixel size (μm^2)	O(20 x 20)	O(10 x 10)	O(50 x 50)
Time resolution (ns RMS)	O(1000)	100	100
In-pixel hit rate (Hz)	54	120 94	54 42 (barrel)
Fake-hit rate (/ pixel / event)	10^{-7}		
Power consumption (mW / cm^2)	35	70	20
Particle hit density (MHz / cm^2)	8.5	120 94	0.8 0.6
Non-Ionising Energy Loss (1 MeV n_{eq} / cm^2)	3×10^{12}	1×10^{16}	6×10^{13}
Total Ionising Dose (Mrad)	0.3	300	3 (barrel)
X/X_0 / layer	0.09% (average) 0.07% (most of active region)	0.1%	1.0%

- A Pb-Pb interaction rate of the ~ 300 kHz corresponds to hit rates similar to 24 MHz pp
- Radiation load dominated by pp due to the longer running time



Key development items / what is available

Key development items

- Front-end circuit
- Pixel geometry
- Readout circuit
- Serial powering

Reticle-sized chip or stitching?

depends on mostly power consumption and distribution

What is available from / currently being developed by ITS3 / EP R&D

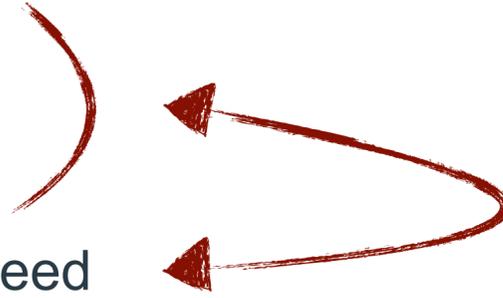
- Slow control interface
- High-speed line drivers (including PLL and linear regulators)
- Lightweight IpGBT data formatting and scrambling
- Voltage and current bias generation circuitry including band gaps
- Analogue monitoring including ADC
- Low leakage current standard cell library



Front-end circuit

- Development goals

- Smaller footprint (to fit inside a 10 μ m pitch pixel)
- Reduced complexity:
fewer transistors and fewer bias currents and bias voltages
- Reduced power consumption for the same performance / speed
- Increased radiation hardness
- Reduced fake-hit rate



Trade-off between
small pixel and
low power consumption
(material budget)

- Development path

- Simulation studies for first validation
- Submission of a small-scale prototype

- Status

- First simulation of a new concept has started

Pixel geometry

- Development goals

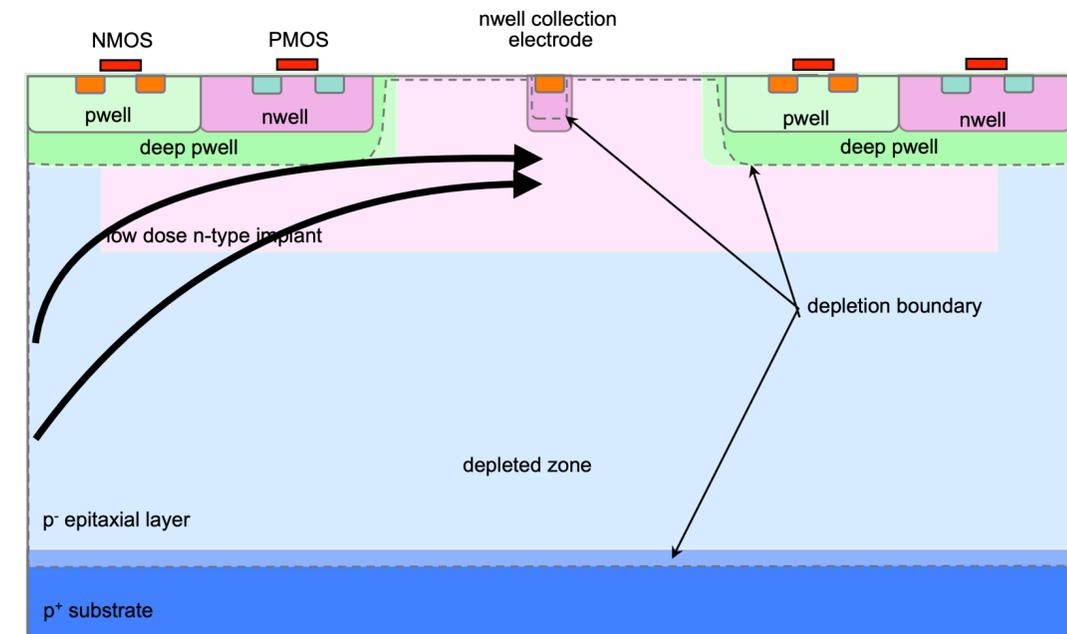
- Radiation hardness: sufficient charge collection at 10^{16} 1 MeV n_{eq}/cm^2
 - Improve charge transport from the pixel edges and corners
- Capacitance reduction:
 - Increase signal voltage for a given charge
 - Reduction of the analogue power consumption $P \propto C^{-2}$

- Development path

- TCAD simulations
- Characterisation of small / medium scale prototypes (APTS/DPTS/CE65)
 - Further detailed study of existing process splits at radiation levels beyond ITS3 and cryogenic temperatures
 - New process splits in upcoming Engineering Runs (ERs)

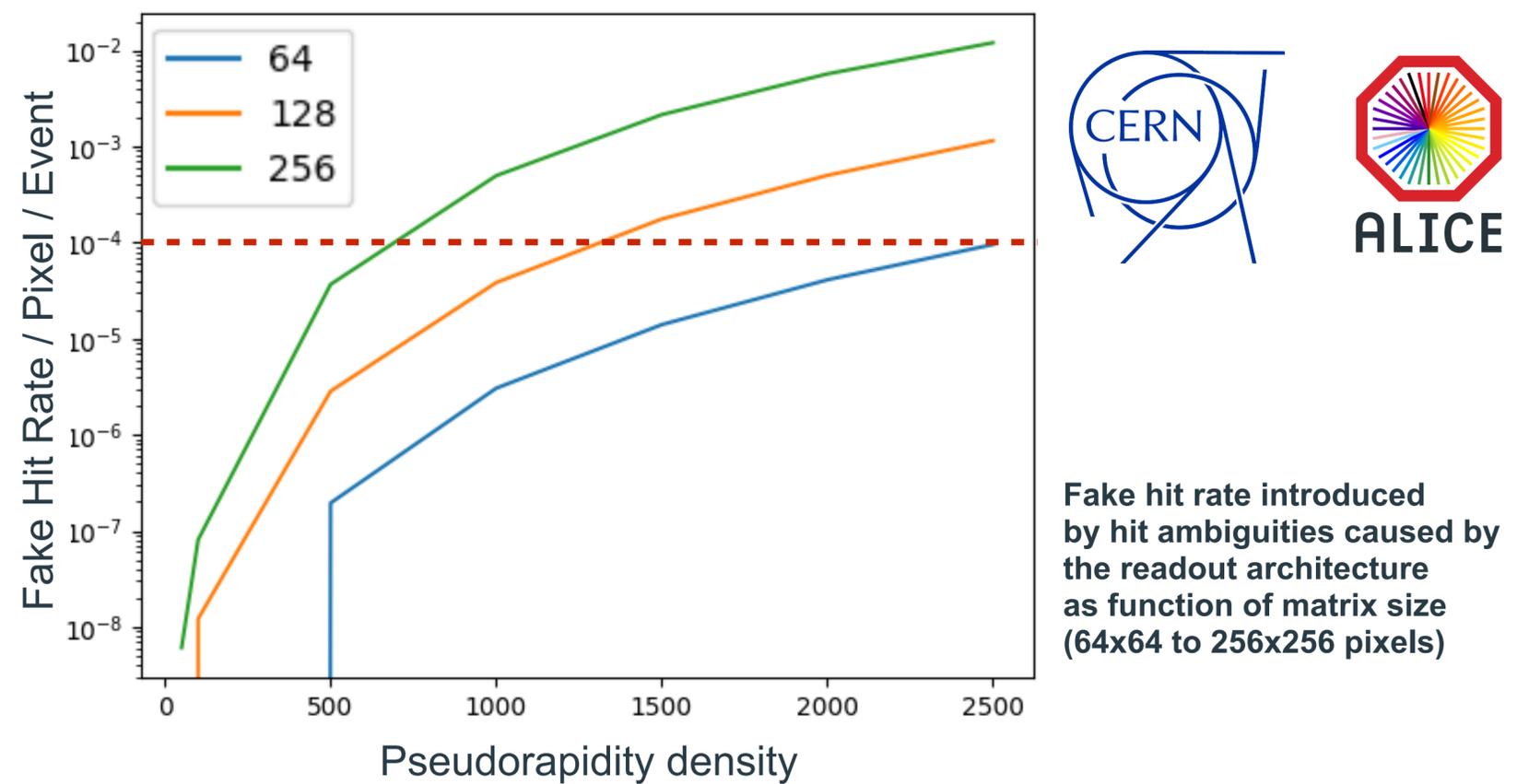
- Status:

- Continuously ongoing process, current focus on ITS3 with limited reverse substrate bias
- Reproduction and understanding of findings from prototype chips



Readout circuit

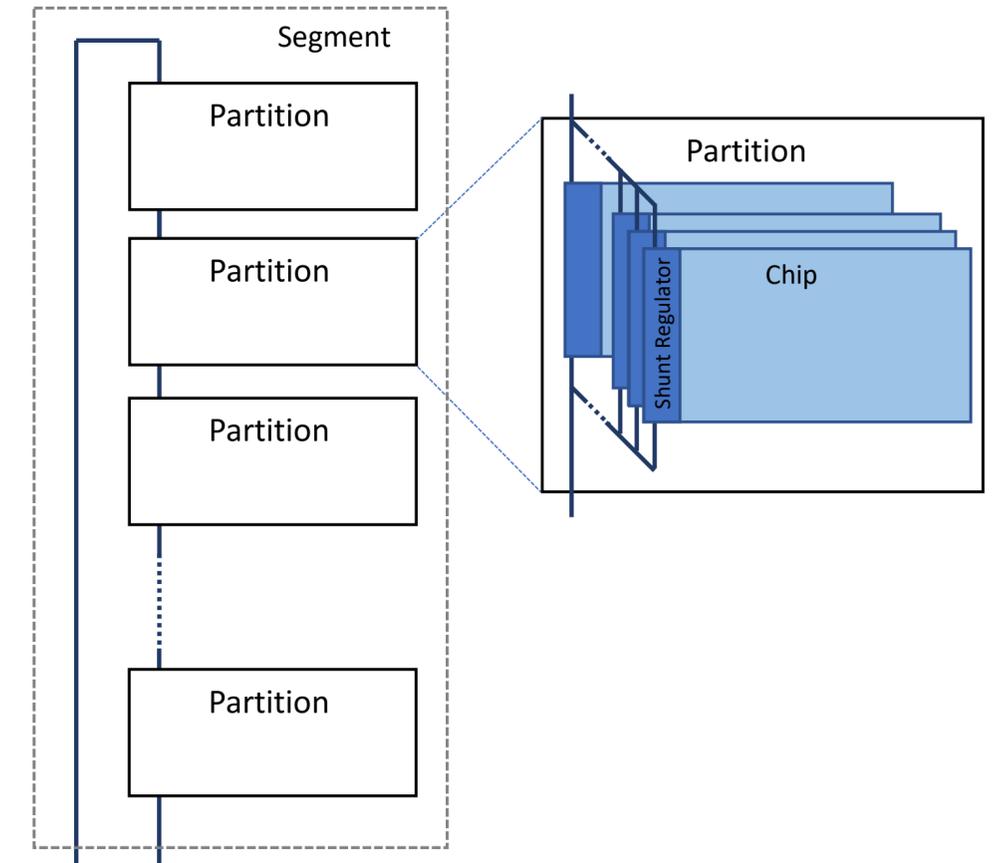
- Development goals
 - Small footprint (to allow 10 μm pixel pitch)
 - Versatility:
 - 24 MHz pp operation \rightarrow time granularity
 - 315 kHz Pb-Pb operation \rightarrow strong occupancy variations
- Development path
 - Architecture simulation in software:
 - Ensure loss less data transport under all expected conditions
 - Obtain expected data throughput and necessary
 - Optimisation of the de-randomization / buffering
 - RTL entry and layout:
 - Assessment of the footprint of the circuitry
 - Validation in a small-scale or full-scale prototype chip



- Status: simulation of architectures ongoing
- Example:
 - Multi-dimensional projections ('Orthopix' [1])
 - Four orthogonal projections
 - Projections are very simple circuit-wise ('wired-OR')
 - Fixed event size independent of the occupancy: $4 \cdot \sqrt{N_{\text{Pixels}}}$
 - Few transitions in the data stream: power efficient
 - No hit losses, only hit ambiguities (\approx fake hits)
 - Overwhelming fake-hit rate for most central Pb-Pb and realistic matrix sizes

Serial powering

- Concept: modules connected in series
 - all modules need to consume the same current
 - ensured by shunt regulators ‘burning’ excess current
 - Baseline for Vertex Detector, Middle Layers
- Development goal
 - Shunt regulator in TPSCo 65 nm process to be integrated in pixel chips
 - Optional: charge pump generating reverse substrate bias
- Development path
 - Characterise performance of existing pixel chips when serially powered
 - Port existing shunt regulator from TJ 180 nm [1,2] or TSMC 65 nm [3] to TPSCo 65 nm
- Status: to be started



Serial powering sketch

[1] D. Gajanana et al. (2016) JINST 11 C03027 Radiation hard analog circuits for ALICE ITS upgrade

[2] A. Habib et al. Shut Regulator for the Serial Powering of the ATLAS CMOS Pixel Detector Modules. 10.1109/TNS.2020.2964333

[3] A. Dimitrievska, A. Stiller NIM A (2019) 958 162091 RD53A: A large-scale prototype chip for the phase II upgrade in the serially powered HL-LHC pixel detectors



Summary and Outlook

- Work slowly ramps up in the shadow of ITS3 activities
- Analogue front-end circuit and pixel optimisation most urgent to be prototyped
- Readout architecture can be mostly evaluated without a prototype submission
- Serial powering
 - Little experience so far in the ALICE context
 - Needed for Vertex Detector, Middle Layers and Outer Tracker

Thanks a lot for your attention!